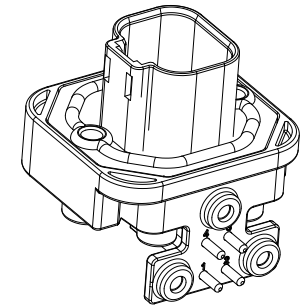
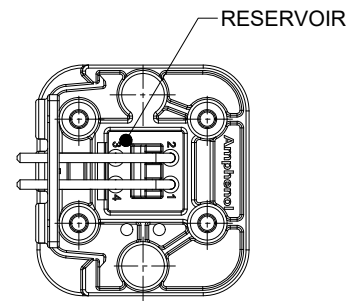
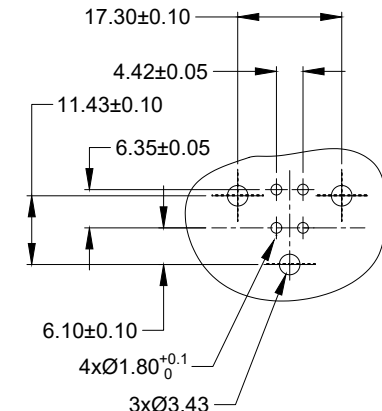
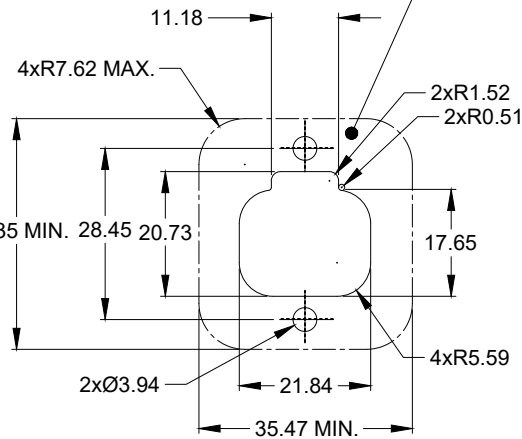


REVISIONS					
REV	ECO	DESCRIPTION	DATE	BY	APPR
A1	--	RELEASE NEW DRAWING	20JUN18	JONY	TOMMY



INTERNAL SEALING SURFACE
FINISH TO BE 3.2/ OR BETTER ∇ 0.13



RECOMMENDED PANEL CUTOUT

RECOMMENDED PCB LAYOUT

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:
HOUSING: THERMOPLASTIC
SEAL: SILICONE RUBBER
CONTACT: COPPER ALLOY
- MODIFICATIONS: FLANGE; PCB MOUNT, RIGHT ANGLE
- SPECIFICATIONS:
3.1 CURRENT RATING: 13 AMPS
3.2 OPERATING TEMPERATURE: -55°C TO +125°C
3.3 DIELECTRIC WITHSTANDING VOLTAGE: LESS THAN 2 MILLIAMPS CURRENT LEAKAGE @ 1500 VOLTS AC.
3.4 INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 25°C.
3.5 MOISTURE RESISTANCE: IP67 (MATED CONDITION)
3.6 MATING CYCLE DURABILITY: 100 CYCLES
3.7 RoHS COMPLIANT
- MATING PART: AT06-4S* PLUG
(* = MODIFICATIONS)
- ALL DIMENSIONS ARE FOR REFERENCE USE ONLY.

AT13-4P-BMXX VARIANTS		
CONTACT PLATING	POTTING OR NOT IN RESERVOIR	PART NUMBER
GOLD	NO POTTING	AT13-4P-BM01
GOLD	POTTING	AT13-4P-BM02
TIN	NO POTTING	AT13-4P-BM03
TIN	POTTING	AT13-4P-BM04

AT13-4P-BMXX		DESCRIPTION		ITEM
QUANTITY	PART NUMBER	MATERIALS LIST		
UNLESS OTHERWISE SPECIFIED 1) All dimensions are in metric (mm). 2) Tolerances are as follows: 1 PL DEC ±0.30 Fractions ±1/64 2 PL DEC ±0.15 Angles ±1° 3 PL DEC ±0.08				
SIGNATURES		DATE		
DRAWN: JONY XIE		20JUN18		
CHECKED: ORION LI		20JUN18		
ENGINEER:				
APPROVAL: TOMMY XIE		20JUN18		
MATERIAL SPECIFICATIONS:				
CUSTOMER:				
THIS DRAWING IS SUPPLIED FOR INFORMATION ONLY. DESIGN FEATURES, SPECIFICATIONS AND PERFORMANCE DATA SHOWN HEREON ARE THE PROPERTY OF THE AMPHENOL CORPORATION. NO RIGHTS OF REPRODUCTION ARE IMPLIED. ALL DIMENSIONS ARE SUBJECT TO NORMAL MANUFACTURING VARIATIONS.				
PROCESS SPECIFICATIONS:				
NEXT ASSY:				
SIZE: B C-	TYPE:	DWG NO: AT13-4P-BMXX	REVISION: A1	
SCALE: NONE			SHEET 1 OF 1	

TITLE: PCB MOUNT RECEPTACLE, 4PIN, RA FLANGE, AT SERIES
DWG NO: AT13-4P-BMXX
REV: A1
SH: 1
OF: 1